

0.56" TRIPLE DIGIT SMD LED DISPLAY

T-5631ASK11-SMD

DESCRIPTION

0.56" (14.2mm) Inch Digit Height.

Super Red Display.

Black Face and White Segment .

Common Cathode

RoHs Compliant

ABSOLUT MAXIMUM RATINGS AT Ta=25°C

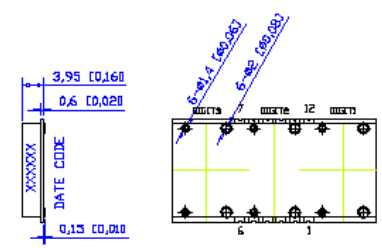
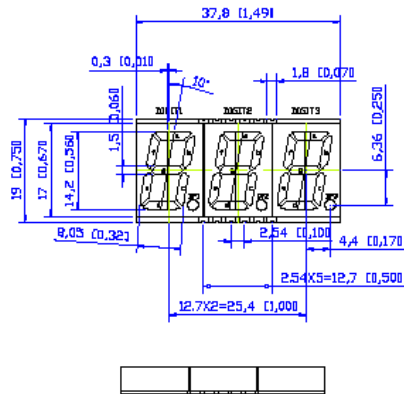
Parameter		UNIT
Power Dissipation Per Seg.	40	mW
Peak Forward Current Per Seg.	120	mA
Forward current Per Seg.	30	mA
Reverse Voltage Per Seg.	5	V
Operation Temperature Range	-40°C TO+80°C	°C
Storage Temperature Range	-40°C TO+100°C	°C
Solder Temperature 1/16 Inch Below Seating Plane For 5 Second At 260 °C		

ELECTRICAL/OPTICAL CHARACTERISTIC AT Ta=25°C

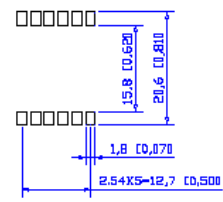
SUPER RED

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Average Luminous Intensity	Iv	4	12		mcd	If=20mA
Peak Emission Wavelength	λ_p		660		nm	If=20mA
Forward Voltage Per Seg.	Vf		1.8	2.2	V	If=20mA
Reverse Current Per Seg.	Ir			10	uA	Vr=5V
Luminous Intensity Matching Ratio	Iv-m			2 : 1		If=20mA

■ Package Dimensions -

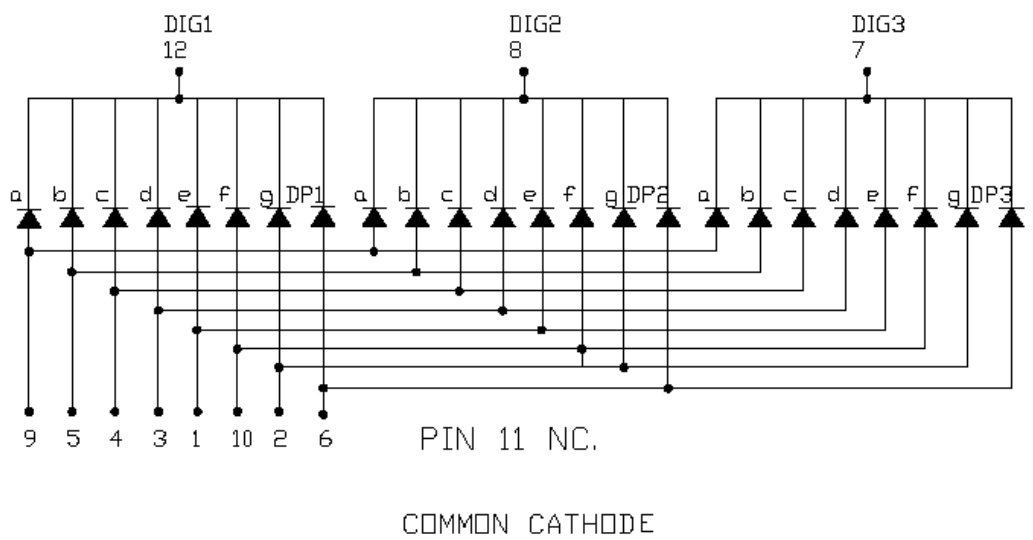


SOLDERING PAD SIZE



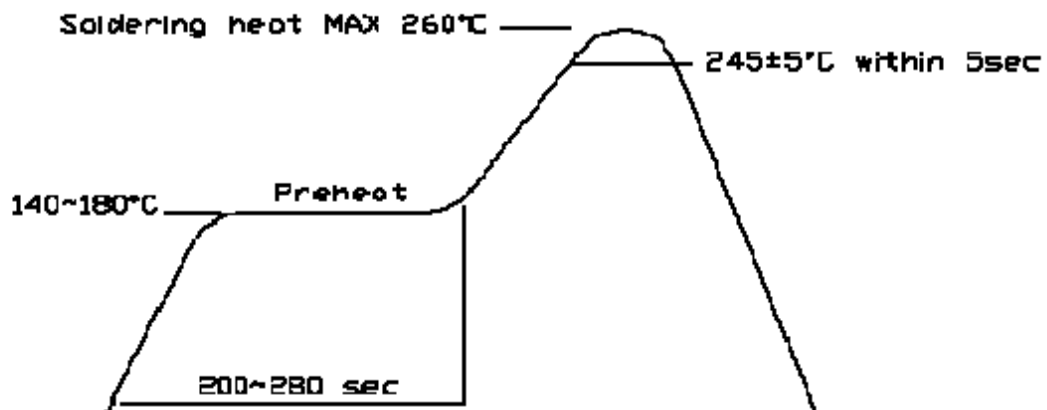
NOTE:
 1. Dimension in millimeter (inch), and tolerance is ± 0.25 (.01) unless otherwise noted.
 2. Specifications are subject to change without notice.

■ Internal Circuit Diagrams -



SMT REFLOW SOLDERING INSTRUCTIONS

SOLDERING HEAT RELIABILITY (DIP):



SOLDERING IRON

Basic spec is ≤ 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C → 1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

1. Customer must finish rework within 5 seconds under 260°C
2. The head of soldering iron cannot touch copper foil.

■ IR Reflow Temperature / Time :

SMT SOLDERING INSTRUCTION

